

50A 1200V Trench Fieldstop IGBT with anti-parallel diode SRE50N120FSUDA
General Description

The SRE50N120FSUDA is a Field Stop Trench IGBT with anti-parallel diode, which offers low switching losses, high energy efficiency and high avalanche ruggedness for soft switching applications such as UPS, solar inverters, etc. The SRE50N120FSUDA is available in TO-247-4.

Features

- High Breakdown Voltage to 1200V
- Advanced Trench Fieldstop technology
 - Low $V_{CE(sat)}$
 - High Ruggedness, Temperature Stability
 - Easy Parallel Switching Capability due to Positive Temperature Coefficient in $V_{CE(SAT)}$
- Soft Current Turn-off Waveforms
- Non-Automotive Qualified

Application

- Solar Inverters
- Uninterrupted Power Supply
- Industrial Power Supplies
- Grid Inverter

Ordering Information

SRE50N120FSUDA□□-□

Circuit Type _____
 Package _____
 T4: TO-247-4

G: Green
 Blank: Tube
 TR: Tape & Reel

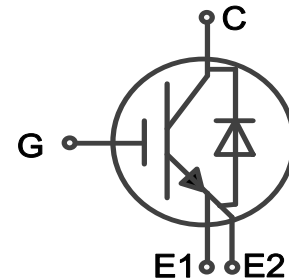
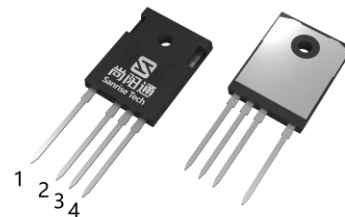
Symbol


Figure 1 Symbol of SRE50N120FSUDA

Package Type


TO-247-4

Pin 1- &backside-Collector; Pin 2-Emitter2
 Pin 3- Kelvin Emitter1; Pin 4- Gate

Figure 2 Package Type of SRE50N120FSUDA

Package	Part Number	Marking ID	Packing Type
TO-247-4	SRE50N120FSUDAT4-G	SRE50N120FSUDAT4G	Tube

50A 1200V Trench Fieldstop IGBT with anti-parallel diode SRE50N120FSUDA
Absolute Maximum Ratings

Parameter		Symbol	Rating	Unit
Collector-emitter voltage		V_{CES}	1200	V
Gate-emitter Voltage		V_{GES}	± 20	V
Transient Gate-emitter Voltage			± 30	V
Continuous Collector Current	$T_C=25^\circ\text{C}$	I_C	100	A
	$T_C=100^\circ\text{C}$		50	
Pulsed Collector Current, Limited by T_{Jmax}		I_{CM}	300	A
Diode Continuous Collector Current ($T_C=100^\circ\text{C}$)		I_F	50	A
Diode Pulsed Current, Limited by T_{Jmax}		I_{FM}	300	A
Power dissipation (TO-247)	$T_C=25^\circ\text{C}$	P_{tot}	500	W
	$T_C=100^\circ\text{C}$		250	W
Power dissipation (TO-247Plus)	$T_C=25^\circ\text{C}$	P_{tot}	650	W
	$T_C=100^\circ\text{C}$		325	W
Maximum Operating Junction Temperature		T_{Jmax}	175 ⁽¹⁾	$^\circ\text{C}$
Storage Temperature		T_{STG}	-55 ~ 150	$^\circ\text{C}$
Lead Temperature (Soldering, 10 sec)		T_{LEAD}	260	$^\circ\text{C}$

Note:

 1. Reliability testing conducted at $T_j=175^\circ\text{C}$.

Thermal Resistance

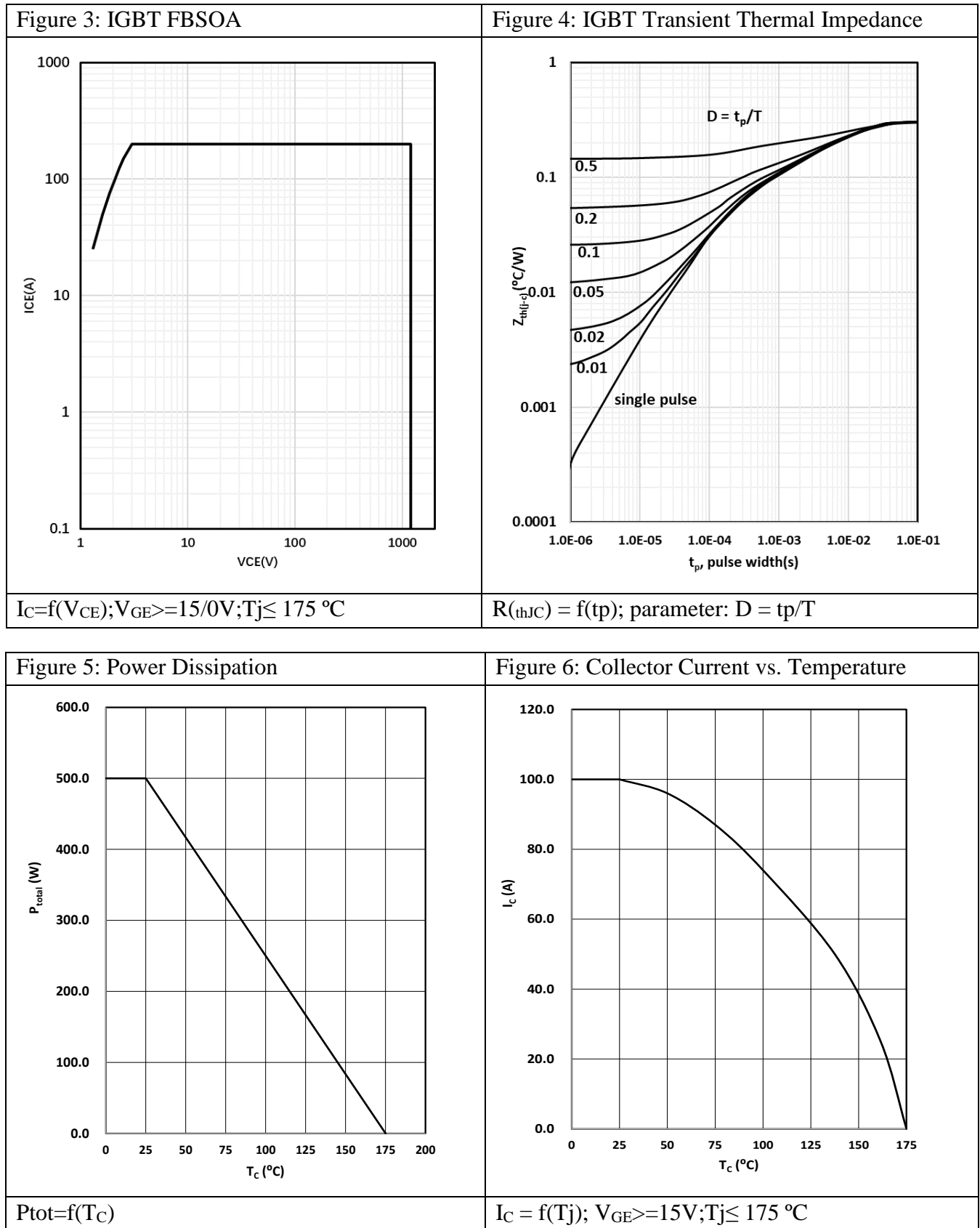
Parameter	Package	Symbol	Min	Typ	Max	Unit
IGBT thermal Resistance, Junction-to-Case	TO-247-4	R_{thJC}	-	-	0.3	$^\circ\text{C}/\text{W}$
Diode thermal Resistance, Junction-to-Case	TO-247-4	R_{thJC}	-	-	0.6	
Thermal Resistance, Junction-to-Ambient	TO-247-4	R_{thJA}	-	-	40	

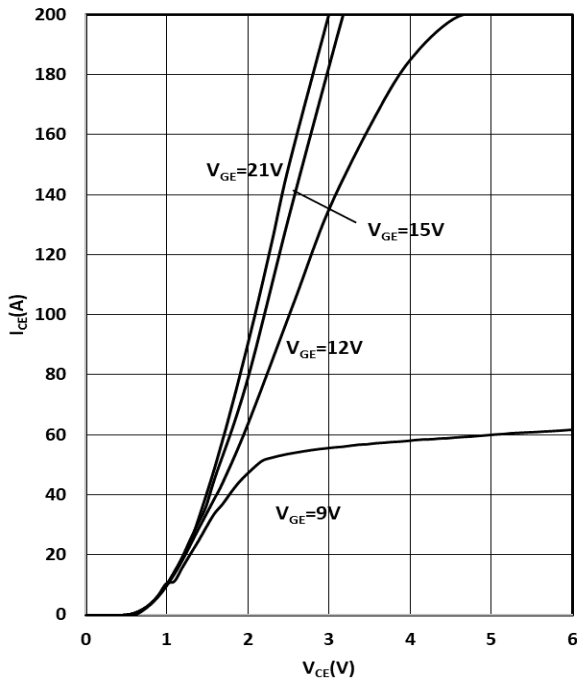
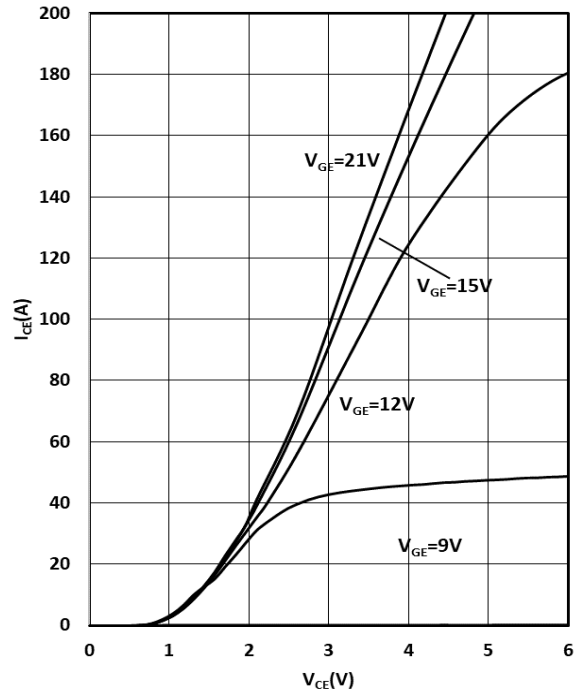
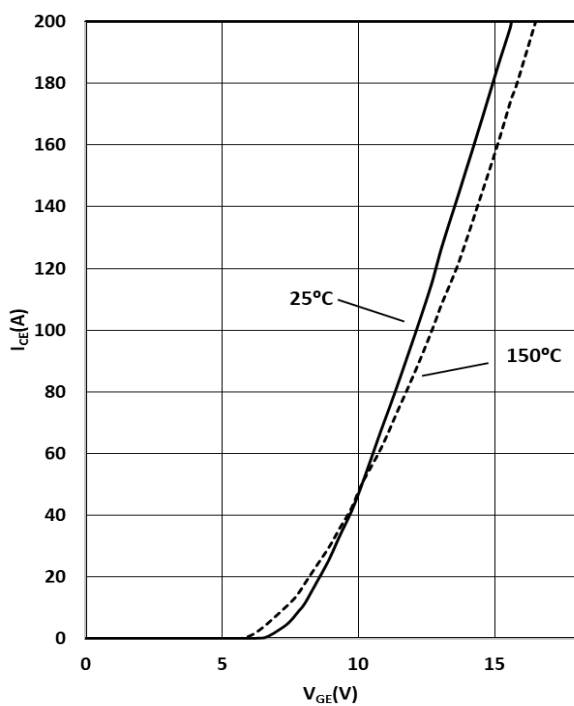
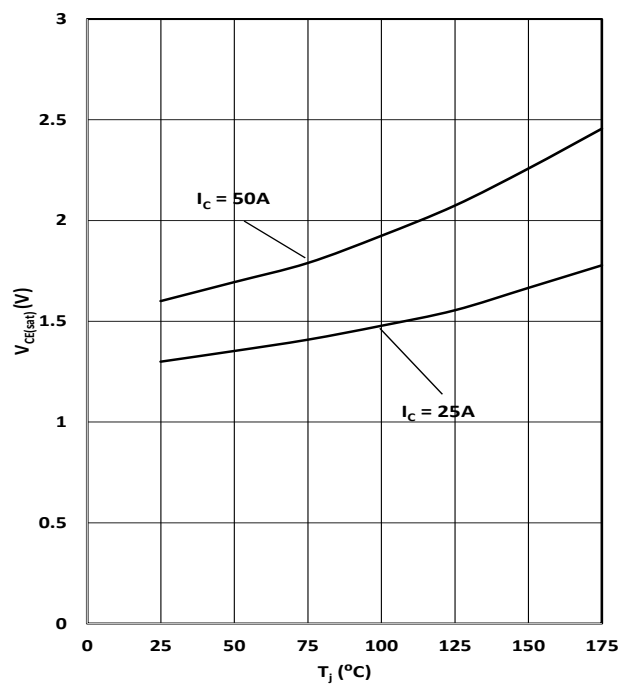
50A 1200V Trench Fieldstop IGBT with anti-parallel diode SRE50N120FSUDA
Electrical Characteristics
 $T_J = 25^\circ\text{C}$, unless otherwise specified.

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit	
Statistic Characteristics							
Collector-emitter Breakdown Voltage	BV_{CES}	$V_{GE}=0V, I_C=500\mu A$	1200			V	
Gate Threshold Voltage	$V_{GE(th)}$	$V_{CE}=V_{GE}, I_C=1.6mA$	4.6	5.4	6.2	V	
Collector-emitter saturation voltage	V_{CEsat}	$V_{GE}=15V, I_C=50A,$ $T_J=25^\circ\text{C}$		1.6	2.0	V	
		$T_J=125^\circ\text{C}$		2.0		V	
		$T_J=175^\circ\text{C}$		2.43		V	
Zero Gate Voltage Collector Current	I_{CES}	$V_{CE}=1200V, V_{GE}=0V$ $T_J=25^\circ\text{C}$			100	μA	
		$T_J=175^\circ\text{C}$			1	mA	
Gate-emitter Leakage Current	Forward	I_{GESF}	$V_{GE}=20V, V_{CE}=0V$			100	nA
	Reverse	I_{GESR}	$V_{GE}=-20V, V_{CE}=0V$			-100	nA
Dynamic Characteristics							
Input Capacitance	C_{IES}	$V_{CE}=25V, V_{GE}=0V,$ $f=1MHz$		4450		pF	
Output Capacitance	C_{OES}			215			
Reverse Transfer Capacitance	C_{RES}			26			
Gate Resistance	R_G	$f=1MHz, \text{Open Drain}$		1.2		Ω	
Turn-on Delay Time	$t_{d(on)}$	$T_J=25^\circ\text{C}$ $V_{CC}=600V, I_C=25A$ $R_G=20\Omega, V_{GE}=0/15V$ Energy losses include "tail" and diode reverse recovery		95		ns	
Rise Time	t_r			25		ns	
Turn-off Delay Time	$t_{d(off)}$			406		ns	
Fall Time	t_f			116		ns	
Turn-on energy	E_{on}			1.5		mJ	
Turn-off energy	E_{off}			0.8		mJ	
Total switching energy	E_{ts}			2.3		mJ	
Turn-on Delay Time	$t_{d(on)}$			96		ns	
Rise Time	t_r			47		ns	
Turn-off Delay Time	$t_{d(off)}$			396		ns	
Fall Time	t_f			135		ns	
Turn-on energy	E_{on}			3.0		mJ	
Turn-off energy	E_{off}			1.8		mJ	
Total switching energy	E_{ts}			4.8		mJ	
Gate to Emitter Charge	Q_{GE}		$V_{CC}=600V, I_C=50A$ $V_{GE}=0 \text{ to } 15V$		57		nC
Gate to Collector Charge	Q_{GC}				66		
Gate Charge Total	Q_G			139			

50A 1200V Trench Fieldstop IGBT with anti-parallel diode SRE50N120FSUDA

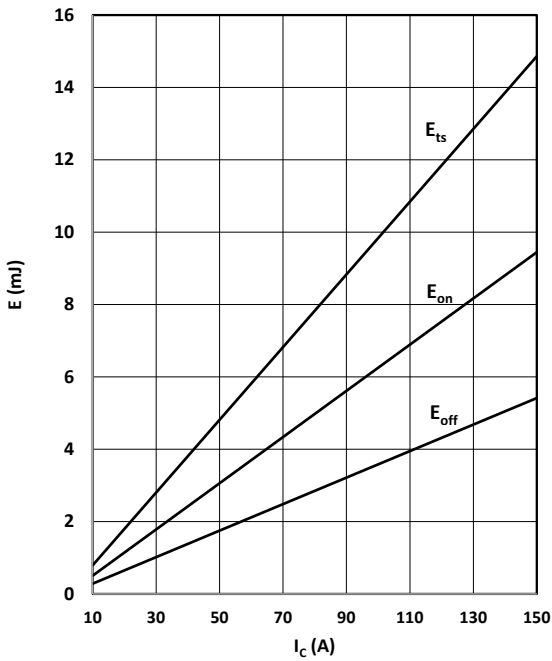
Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Reverse Diode Characteristics						
Diode Forward Voltage	V_F	$I_F=25A$ $T_j=25^\circ C$		1.71	2.1	V
		$I_F=25A$ $T_j=100^\circ C$		1.54		
		$I_F=25A$ $T_j=175^\circ C$		1.39		
		$I_F=50A$ $T_j=25^\circ C$		2.05	2.45	
		$I_F=50A$ $T_j=100^\circ C$		1.87		
		$I_F=50A$ $T_j=175^\circ C$		1.72		
Reverse Recovery Time	t_{rr}	$T_j=25^\circ C$ $V_R=600V, I_F=50A$ $dI_F/dt=1200A/us$		130		ns
Reverse Recovery Charge	Q_{rr}			2.47		μC
Peak Reverse Recovery Current	I_{rrm}			38		A
Diode peak rate of fall of reverse Recovery current during t_b	di_{rr}/dt			-622		A/us
Reverse Recovery Time	t_{rr}	$T_j=100^\circ C$ $V_R=600V, I_F=50A$ $dI_F/dt=1200A/us$		204		ns
Reverse Recovery Charge	Q_{rr}			5.18		μC
Peak Reverse Recovery Current	I_{rrm}			56		A
Diode peak rate of fall of reverse Recovery current during t_b	di_{rr}/dt			-648		A/us
Reverse Recovery Time	t_{rr}	$T_j=150^\circ C$ $V_R=600V, I_F=50A$ $dI_F/dt=1200A/us$		258		ns
Reverse Recovery Charge	Q_{rr}			7.88		μC
Peak Reverse Recovery Current	I_{rrm}			69		A
Diode peak rate of fall of reverse Recovery current during t_b	di_{rr}/dt			-704		A/us

50A 1200V Trench Fieldstop IGBT with anti-parallel diode SRE50N120FSUDA
Typical Performance Characteristics


50A 1200V Trench Fieldstop IGBT with anti-parallel diode SRE50N120FSUDA
Figure 7: Typical Output Characteristics

 $I_C = f(V_{CE}); T_j = 25^\circ\text{C}; \text{parameter: } V_{GE}$
Figure 8: Typical Output Characteristics

 $I_C = f(V_{CE}); T_j = 175^\circ\text{C}; \text{parameter: } V_{GE}$
Figure 9: Typical transfer characteristic

 $I_C = f(V_{GE}); V_{CE} = 20\text{V}$
Figure 10: Typical collector-emitter saturation voltage as a function of junction temperature

 $V_{CE} = f(T_j); V_{GE} = 15\text{V}$

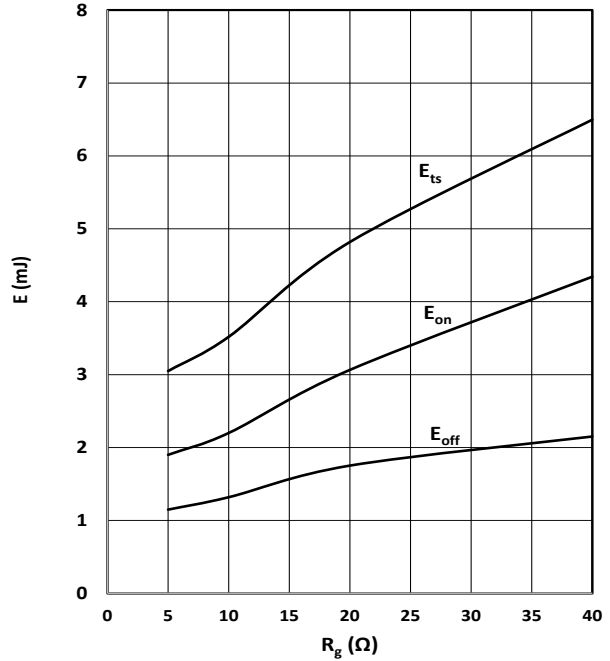
50A 1200V Trench Fieldstop IGBT with anti-parallel diode SRE50N120FSUDA

Figure 11: Typical switching energy losses as a function of collector current



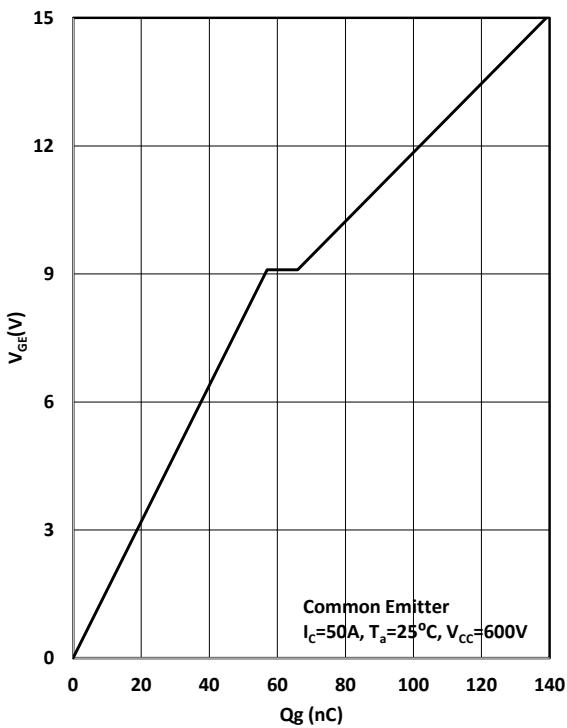
$$E=f(I_C) ; V_{CE}=600V; T_j=25^{\circ}C; R_G=20\Omega$$

Figure 12: Typical switching energy losses as a function of gate resistor



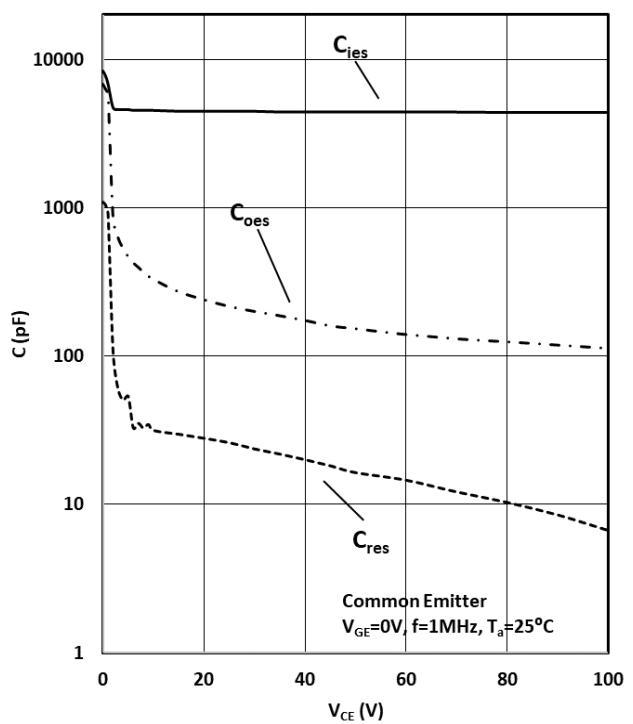
$$E=f(R_G) ; V_{CE}=600V; T_j=25^{\circ}C; I_C=50A$$

Figure 13: Typical Gate Charge



$$V_{GE}=f(Q_g), I_C=50A$$

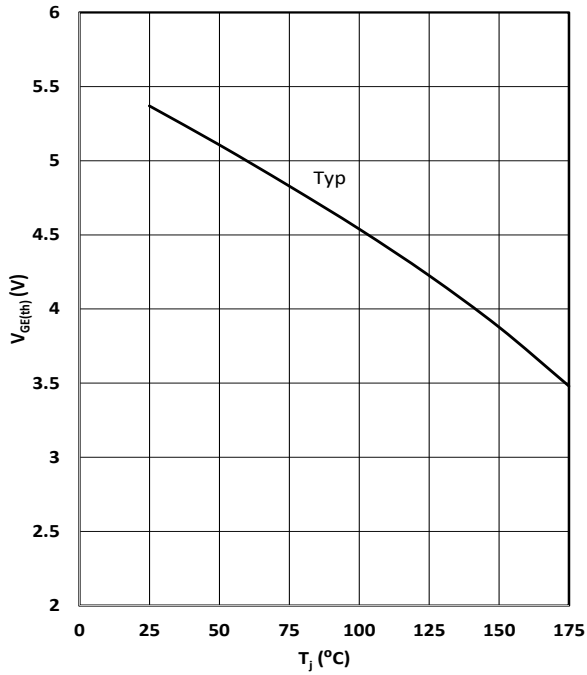
Figure 14: Typical Capacitances



$$C=f(V_{CE}); V_{GE}=0; f=1MHz$$

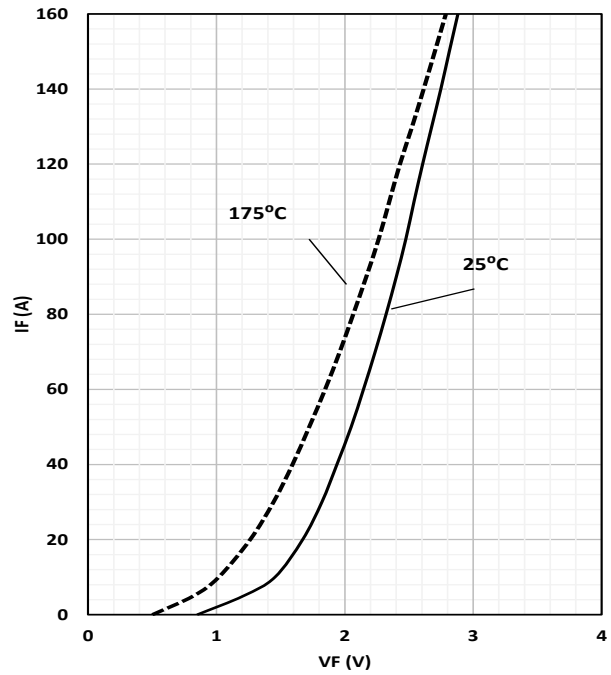
50A 1200V Trench Fieldstop IGBT with anti-parallel diode SRE50N120FSUDA

Figure 15: Typ. emitter threshold voltage as a function of junction temperature

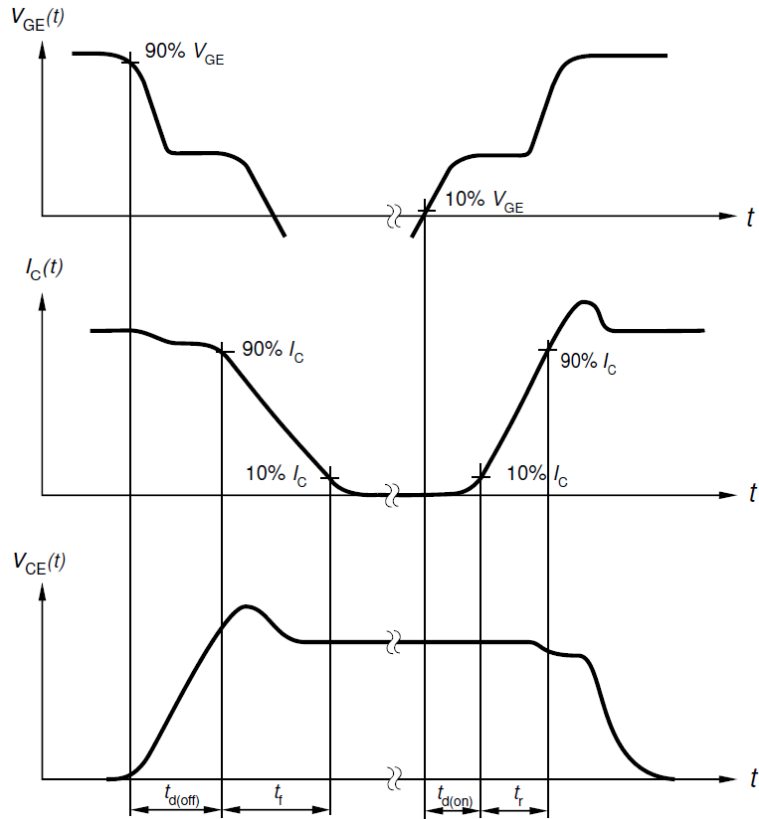
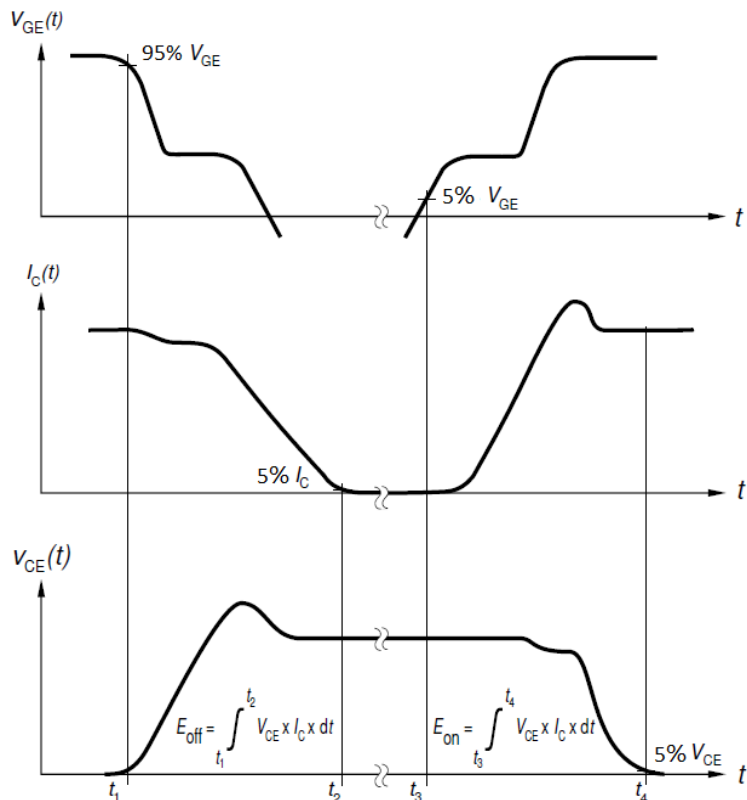


$$V_{GE} = f(T_j); I_{CE} = 1.6 \text{ mA}$$

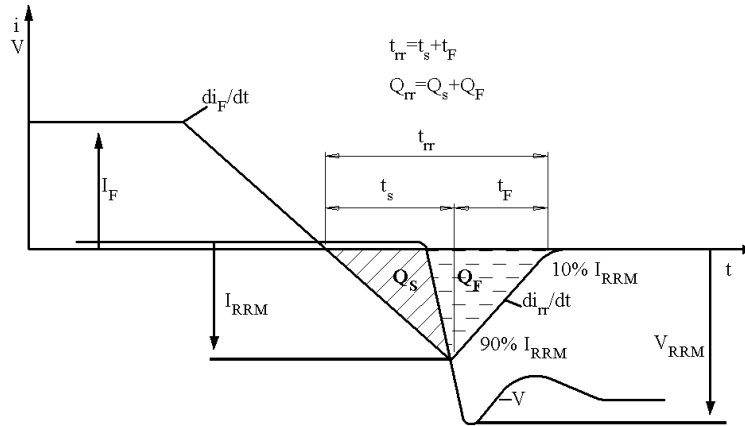
Figure 16: Typical diode forward current as a function of forward voltage



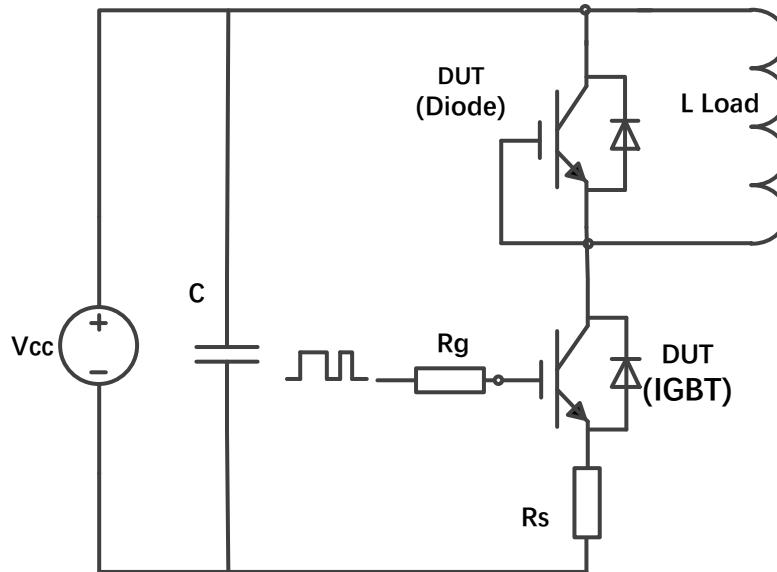
$$V_F = f(I_F);$$

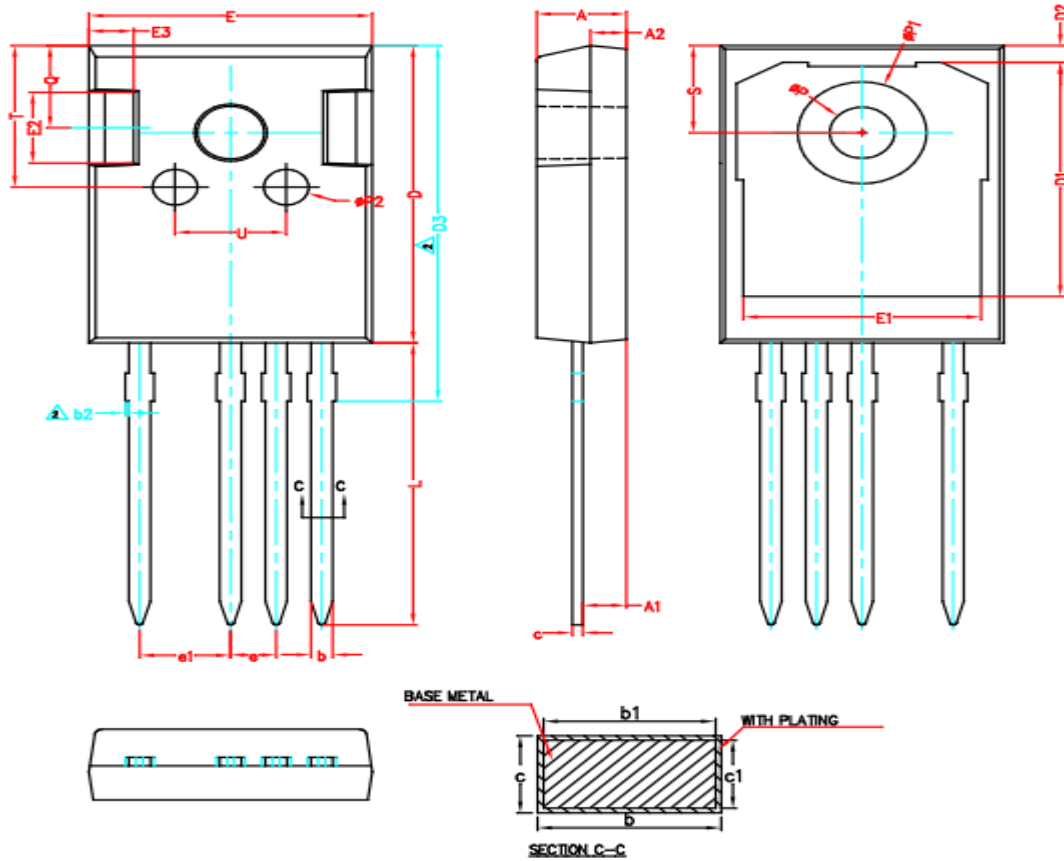
Test Circuits
1. Definition Switching times

2. Definition Switching losses


3. Definition Diode Switching Characteristics



4. Dynamic test circuit



Mechanical Dimensions
TO-247-4
Unit: mm


Symbol [↵]	Dimensions (mm) [↵]			Symbol [↵]	Dimensions (mm) [↵]		
	Min. [↵]	Typ. [↵]	Max. [↵]		Min. [↵]	Typ. [↵]	Max. [↵]
A [↵]	4.90 [↵]	5.00 [↵]	5.10 [↵]	E1 [↵]	13.10 [↵]	13.30 [↵]	13.50 [↵]
A1 [↵]	2.31 [↵]	2.41 [↵]	2.51 [↵]	E2 [↵]	4.90 [↵]	5.00 [↵]	5.10 [↵]
A2 [↵]	1.90 [↵]	2.00 [↵]	2.10 [↵]	E3 [↵]	2.40 [↵]	2.50 [↵]	2.60 [↵]
b [↵]	1.16 [↵]	- [↵]	1.29 [↵]	e [↵]	2.44 [↵]	2.54 [↵]	2.64 [↵]
b1 [↵]	1.15 [↵]	1.2 [↵]	1.25 [↵]	e1 [↵]	4.98 [↵]	5.08 [↵]	5.18 [↵]
b2 [↵]	0.00 [↵]	- [↵]	0.20 [↵]	L [↵]	19.80 [↵]	19.92 [↵]	20.10 [↵]
c [↵]	0.59 [↵]	- [↵]	0.66 [↵]	P [↵]	3.50 [↵]	3.60 [↵]	3.70 [↵]
c1 [↵]	0.58 [↵]	0.60 [↵]	0.62 [↵]	P1 [↵]	- [↵]	- [↵]	7.40 [↵]
D [↵]	20.90 [↵]	21.00 [↵]	21.10 [↵]	P2 [↵]	2.40 [↵]	2.50 [↵]	2.60 [↵]
D1 [↵]	16.25 [↵]	16.55 [↵]	16.85 [↵]	Q [↵]	5.60 [↵]	- [↵]	6.00 [↵]
D2 [↵]	1.05 [↵]	1.20 [↵]	1.35 [↵]	S [↵]	- [↵]	6.15BSC [↵]	- [↵]
D3 [↵]	24.97 [↵]	25.12 [↵]	25.27 [↵]	T [↵]	9.80 [↵]	- [↵]	10.20 [↵]
E [↵]	15.70 [↵]	15.80 [↵]	15.90 [↵]	U [↵]	6.00 [↵]	- [↵]	6.40 [↵]



Shenzhen Sanrise Technology Co., LTD

<http://www.sanrise-tech.com>

IMPORTANT NOTICE

Shenzhen Sanrise Technology Co., LTD. reserves the right to make changes without further notice to any products or specifications herein. Shenzhen Sanrise Technology Co., LTD. does not assume any responsibility for use of any its products for any particular purpose, nor does Shenzhen Sanrise Technology Co., LTD. assume any liability arising out of the application or use of any its products or circuits. Shenzhen Sanrise Technology Co., LTD. does not convey any license under its patent rights or other rights nor the rights of others.

Main Site:

- Headquarter

Shenzhen Sanrise Technology Co., LTD.
A1206, Skyworth building, No. 008, gaoxinnan 1st
Road, Gaoxin District, Yuehai street, Nanshan District,
ShenZhen, P.R. China
Tel: +86-755-22953335
Fax: +86-755-22916878

- Shanghai Office

Shenzhen Sanrise Technology Co., LTD.
Rm.401, Building B, No. 666, Zhangheng Road,
Zhangjiang Hi-Tech Park, Shanghai, P.R.China
Tel: +86-21-68825918